

Amendments to the Claims:

This listing of claims replaces all prior versions and listings of claims in the application:

Listing of Claims:

1. (Currently Amended) A leadframe-based housing for a surface-mountable electronic component, with a leadframe having a front side and a back side and comprising at least two electrical connector strips [[(2a, 2b)]], and an injection-molded or transfer-molded housing base body [[(8a, 8b)]] made from an electrically insulating injection compound and comprising a front portion disposed at the front side of said leadframe and a back wall disposed at the back side of said leadframe, ~~characterized in that~~ wherein said leadframe comprises at least one injection aperture [[(24)]] through which said housing base body is injected onto said leadframe from a back side of said leadframe.
2. (Currently Amended) The housing as described in claim 1, ~~characterized in that~~ wherein said injection aperture [[(24)]] is disposed in one of said electrical connector strips.
3. (Currently Amended) The housing as described in claim 1[[or 2]], wherein said back wall has a thickness of less than 0.3 mm and more than 0 mm.
4. (Currently Amended) The housing as described in ~~at least one of claims 1 to 3~~ claim 1 for a radiation-emitting and/or radiation-detecting component, wherein said housing base body [[(8a, 8b)]] comprises in said front portion [[(8a)]] a recess for receiving a radiation-emitting and/or radiation-detecting chip, said injection aperture [[(24)]] being disposed in the region of a wall of said front portion delimiting said recess.

5. (Original) The housing as described in claim 4, wherein said recess is formed as a reflector.

6. (Currently Amended) A leadframe ribbon comprising at least one housing as described in ~~one of claims 1 to 5~~ claim 1.

7. (Currently Amended) An electronic component having a housing as described in ~~at least one of claims 1 to 5~~ claim 1, which comprises at least one chip[[(16)]].

8. (Currently Amended) The electronic component as described in claim 7, wherein said at least one chip[[(16)]] is a radiation-emitting and/or radiation-detecting chip.

9. (Currently Amended) The electronic component as described in claim 7[[or 8]], wherein said chip[[(16)]] is disposed on one of the two connector strips[[(2a)]] and is electrically connected to the second connector strip[[(2b)]] by means of an electrical connecting line[[(17)]].

10. (Currently Amended) The electronic component as described in claim 7[[or 8]], wherein said chip[[(16)]] is disposed on a mounting area of said housing base body and is electrically connected to each of said electrical connector strips[[(2a, 2b)]] by means of in each case one electrical connecting line[[(17)]].

11. (Currently Amended) The electronic component as described in claim 7[[or 8]], wherein said chip[[(16)]] is disposed on a thermally well-conducting chip carrier leading through said housing base body to the back side and is electrically connected to each of said electrical connector strips[[(2a, 2b)]] by means of in each case one electrical connecting line [[(17)]].

12. (Currently Amended) The electronic component as described in ~~at least one of claims 8 to 11~~ claim 1, ~~comprising a housing with reference to claim 4 or 5~~, wherein said recess is filled with an injection compound that is transparent to radiation emitted by and/or to be detected by said chip.

13. (Currently Amended) A method for producing a leadframe-based housing as described in ~~one of claims 1 to 5~~ claim 1, comprising the following method steps:

- a) preparing said leadframe comprising said two connector strips and said injection aperture[[(24)]],
- b) applying to said leadframe an injection mold that forms around said leadframe a cavity for creating said housing base body and inserting an injection nozzle into or placing it against said injection aperture[[(24)]],
- c) injecting the injection compound into said cavity,
- d) at least partially solidifying the injection compound, and
- e) opening the injection mold, including the removal of said injection nozzle.

14. (Original) The method as described in claim 13, wherein a thermoplastic material is used as the injection compound.

15. (New) The electronic component comprising a housing with reference to claim 4, wherein said recess is filled with an injection compound that is transparent to radiation emitted by and/or to be detected by said chip.